Title (en)

PD AND PD-NI ELECTROLYTE BATHS

Title (de)

PD- UND PD-NI-ELEKTROLYTBÄDER

Title (fr)

BAINS D'ÉLECTROLYTE AU PD ET AU PD-NI

Publication

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Application

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Priority

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Abstract (en)

[origin: US8900436B2] The present invention relates to an electrolyte for the electrochemical deposition of palladium or palladium alloys on metallic or conductive substrates. The invention likewise relates to a corresponding electroplating process using this electrolyte and specific palladium salts which can be advantageously used in this process.

IPC 8 full level

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CPC (source: EP US)

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